



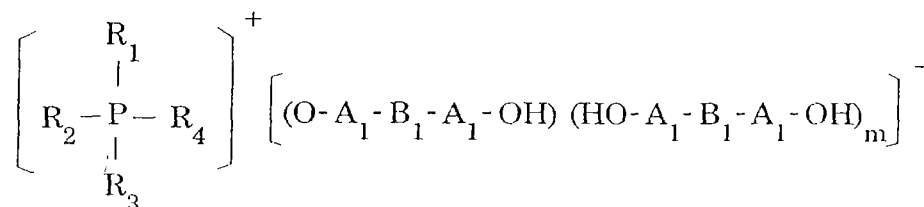
ABSTRACT

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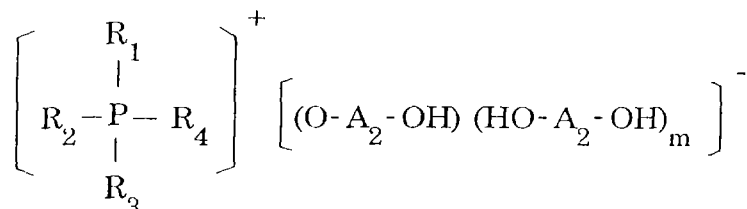
THERMOSETTING RESIN COMPOSITION, EPOXY RESIN MOLDING MATERIAL AND SEMICONDUCTOR DEVICE

An epoxy resin molding material which comprises as essential components thereof (A) a compound having at least two epoxy groups in one molecule, (B) a compound having at least two phenolic hydroxyl groups in one molecule, (C) a molecular compound represented by any one of general formulae (1) and (2) and (D) an inorganic filler. The material exhibits an increased curing rate and an excellent storage stability.

General formula (1):



General formula (2):



(P represents phosphorus atom, R_1 , R_2 , R_3 and R_4 each represent a substituted or unsubstituted aromatic group or an alkyl group, A_1 and A_2 each represent a divalent aromatic group, B_1 represents a single bond, a divalent group selected from ether groups, sulfone groups, sulfide groups and carbonyl groups or a divalent organic group having 1 to 13 carbon atoms and $0 \leq m \leq 0.75$.)

FIGURE: NONE



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